

1. General description

Dual common cathode power Schottky diode designed for high frequency switched mode power supplies in a TO263 (D2PAK) plastic package.



2. Features and benefits

- High junction temperature up to 175 °C
- Low forward voltage drop, negligible switching losses
- High efficiency

3. Applications

- DC to DC converters
- Freewheeling diode
- OR-ing diode
- Switched mode power supply rectifier

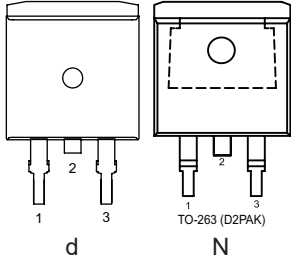
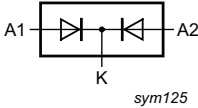
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V _{RRM}	repetitive peak reverse voltage			170			V
I _{F(AV)}	average forward current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 158 °C; per diode; Fig. 1 ; Fig. 2 ; Fig. 3		15			A
I _{O(AV)}	average output current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 158 °C; both diodes conducting		30			A
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 15 A; T _j = 25 °C; per diode; Fig. 6		-	0.81	0.90	V
I _R	reverse current	V _R = 170 V; T _j = 25 °C; per diode; Fig. 7 ; Fig. 8		-	0.2	10	µA

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode 1		
2	K	cathode		
3	A2	anode 2		
mb	K	mounting base; connected to cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WN3S30H170CBT	TO263	WN3S30H170CBTJ	Reel	800	TO263d	17-Mar-2023
					TO263N	26-Sep-2016

7. Marking

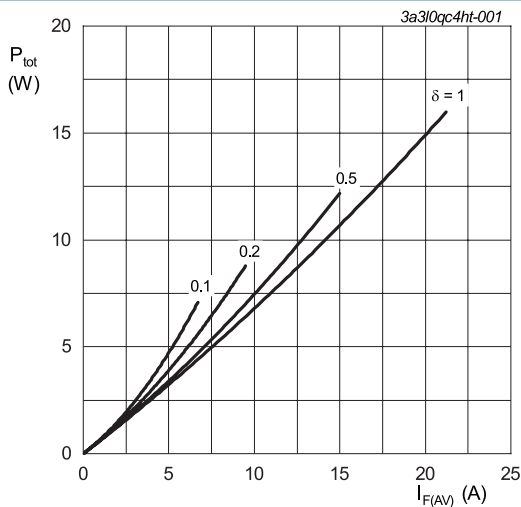
Table 4. Marking codes

Type number	Marking codes	
	Assembly factory: d	Assembly factory: N
WN3S30H170CBT	WN3S30H 170CBT	WN3S30 H170CBT

8. Limiting values

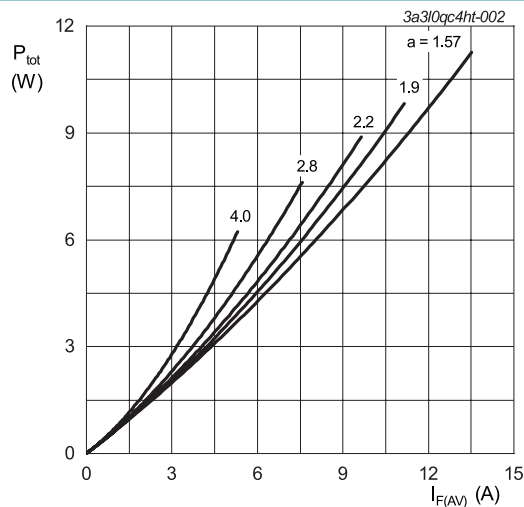
Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V _{RRM}	repetitive peak reverse voltage			170	V
V _{RWM}	crest working reverse voltage			170	V
V _R	reverse voltage	DC		170	V
I _{F(AV)}	average forward current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 158 °C; per diode; Fig. 1; Fig. 2; Fig. 3		15	A
I _{O(AV)}	average output current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 158 °C; both diodes conducting		30	A
I _{FSM}	non-repetitive peak forward current	t _p = 10 ms; T _{j(init)} = 25 °C; sine-wave pulse; per diode; Fig. 4		300	A
		t _p = 8.3 ms; T _{j(init)} = 25 °C; sine-wave pulse; per diode		330	A
T _{stg}	storage temperature			-40 to 175	°C
T _j	junction temperature			-40 to 175	°C



$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$
 $V_o = 0.613 \text{ V}; R_s = 0.0066 \text{ } \Omega$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values; per diode



$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$
 $V_o = 0.613 \text{ V}; R_s = 0.0066 \text{ } \Omega$

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values; per diode

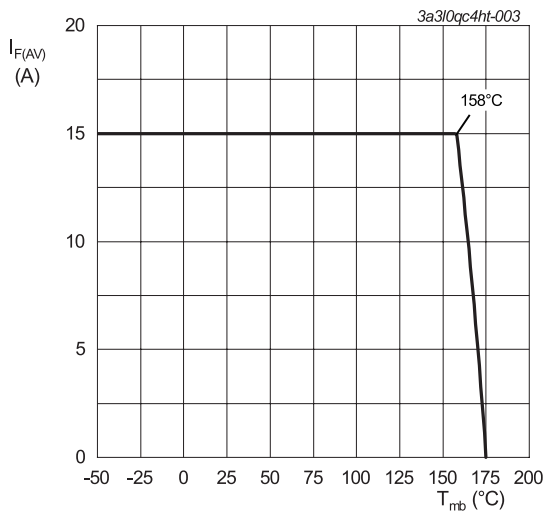


Fig. 3. Average forward current as a function of mounting base temperature; maximum values; per diode

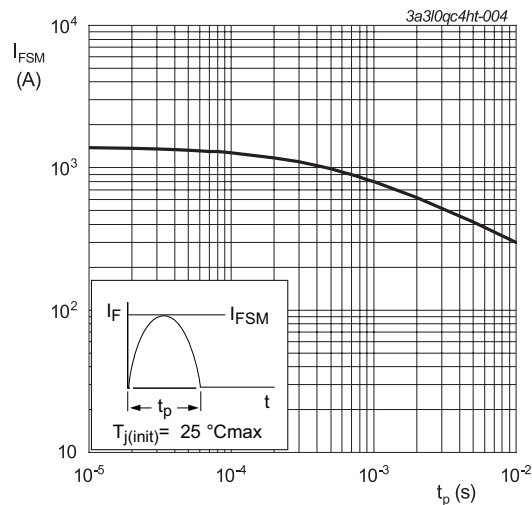
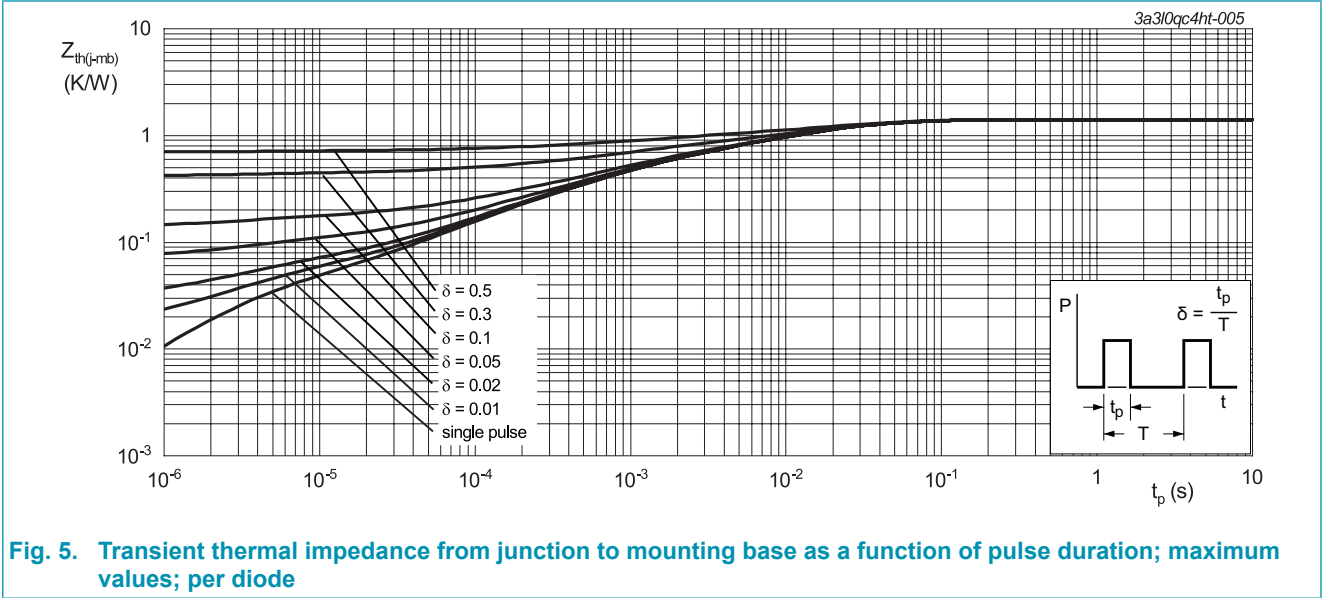


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values; per diode

9. Thermal characteristics

Table 6. Thermal characteristics

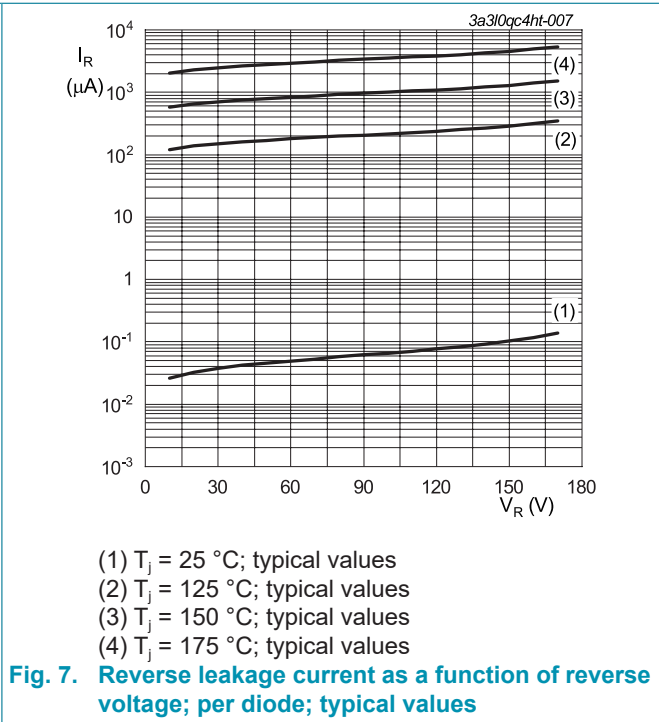
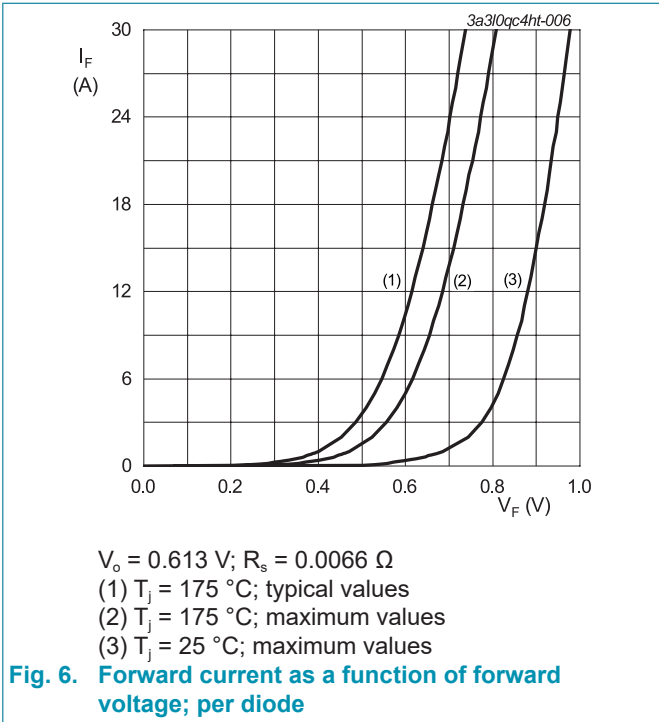
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	per diode; Fig. 5		-	-	1.4	K/W
		both diodes conducting		-	-	0.7	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W

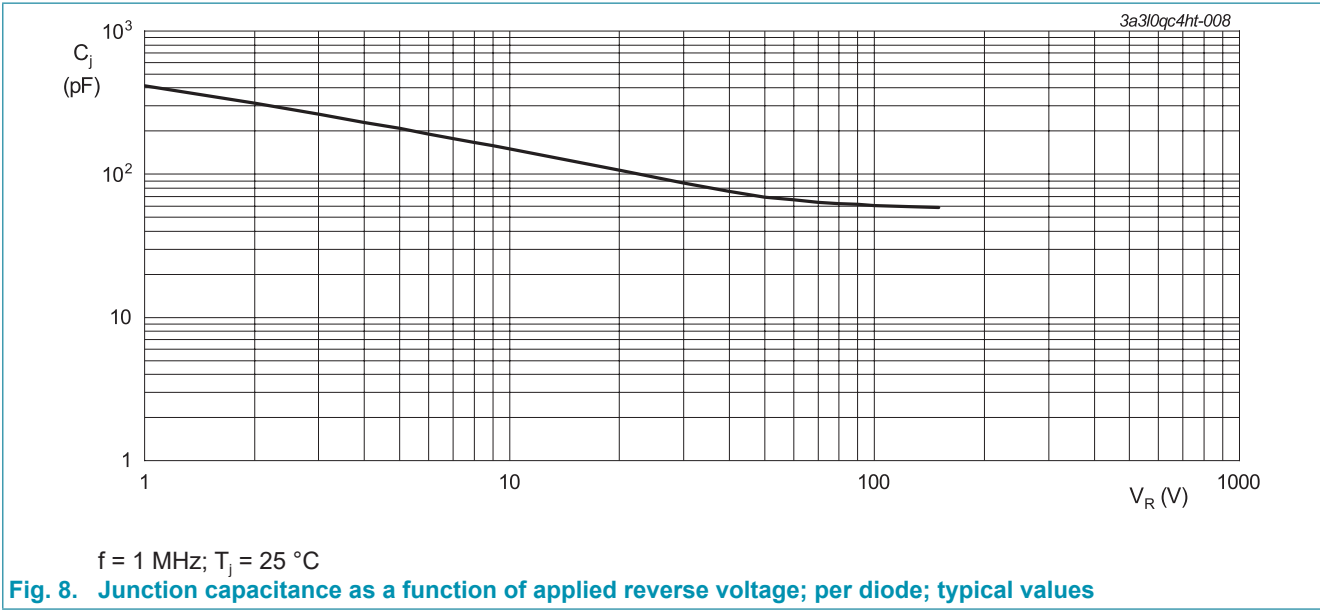


10. Characteristics

Table 7. Characteristics

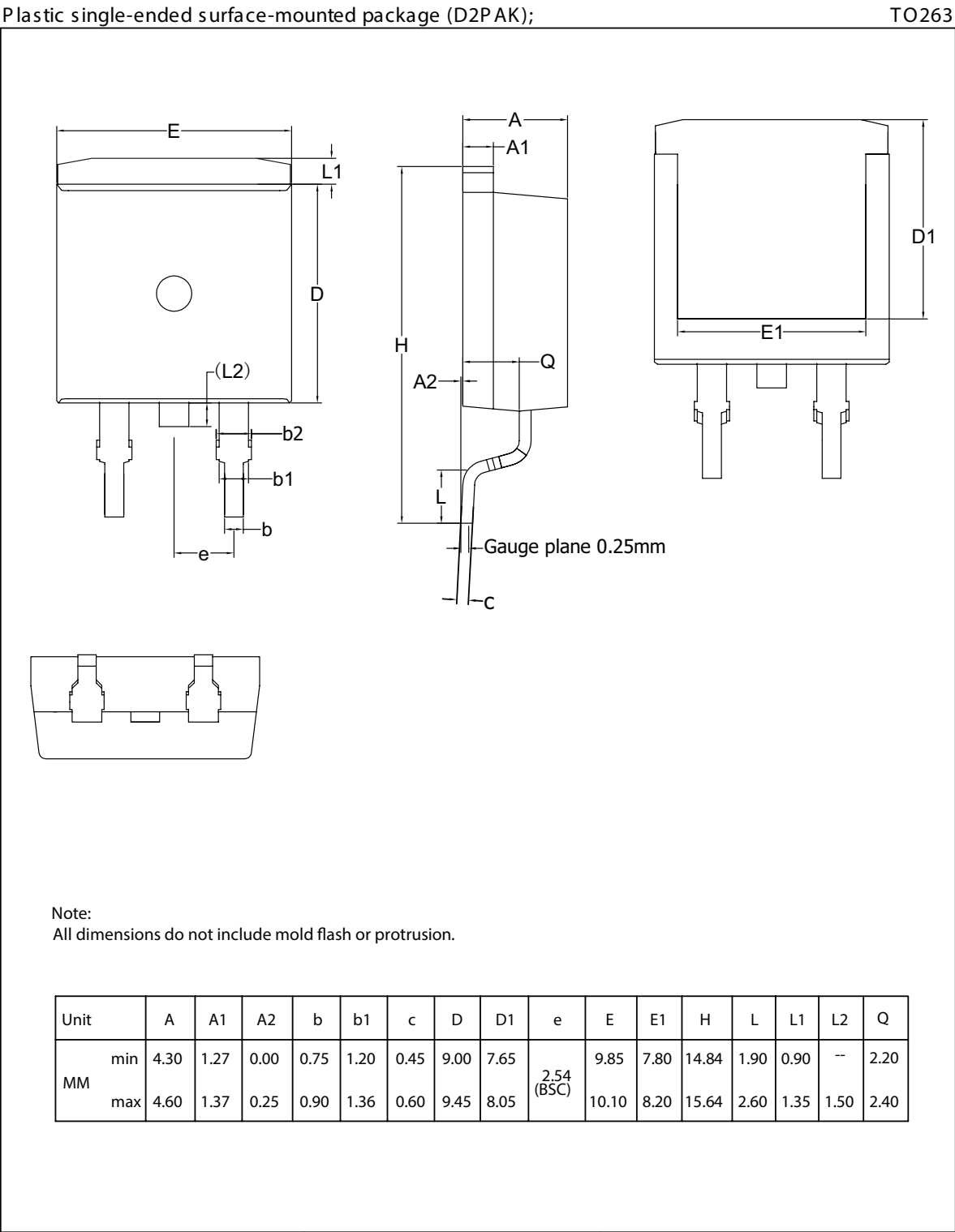
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 15 A; T _J = 25 °C; per diode; Fig. 6		-	0.81	0.90	V
		I _F = 15 A; T _J = 125 °C; per diode; Fig. 6		-	0.67	-	V
I _R	reverse current	V _R = 170 V; T _J = 25 °C; per diode; Fig. 7 ; Fig. 8		-	0.2	10	μA
		V _R = 170 V; T _J = 125 °C; per diode; Fig. 7 ; Fig. 8		-	0.4	10	mA





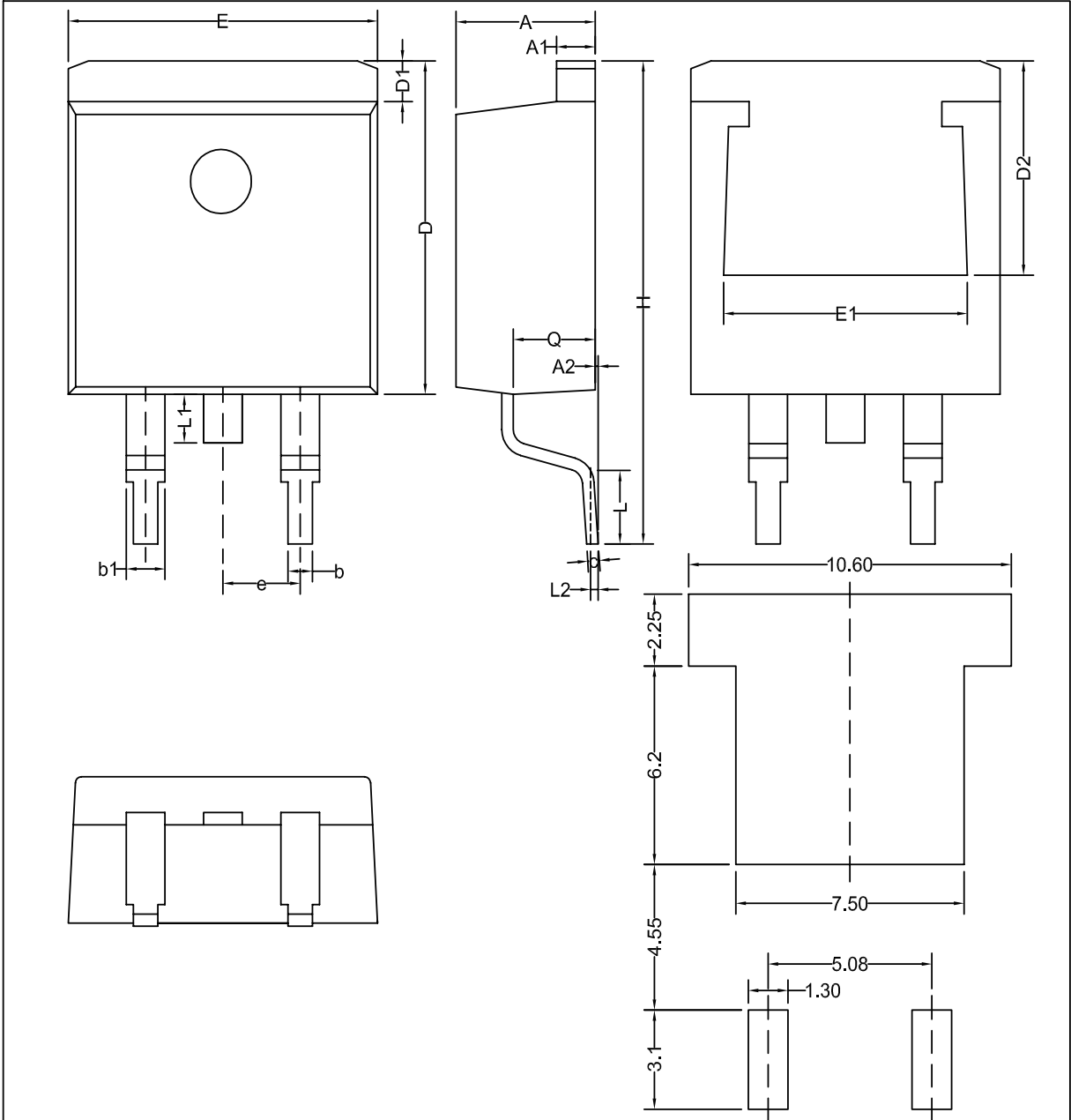
11. Package outline

Assembly factory: d



Assembly factory: N

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) TO263



Recommended Footprint

Unit	A	A1	A2	b	b1	c	D	D1	D2	e	E	E1	H	L	L1	L2	Q
min	4.10	1.22	0.00	0.60	1.05	0.34	---	1.20	6.60	2.54 (BSC)	9.70	7.80	14.80	2.10	---	0.25 (BSC)	2.20
max	4.70	1.40	0.25	0.90	1.45	0.64	11.00	1.60	---	---	10.30	---	15.80	2.90	1.75	---	2.79

12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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